# Nano Sim Card Connector Multicomp

: High Temperature Thermoplastic, UL94V-0

: Plated 30u" Ni Over All Au Gold 0.8u"

: Plated 30u" Ni Over All, PAD Au 0.8u"

: Copper Alloy

: 0.5A max. : 125V AC/DC : 95% R.H. Max. : 100mΩ max.

: 1000MΩ min./500V DC

: 3000 Insertions

: SUS

# Specification

### Material

Insulator Contact Shell

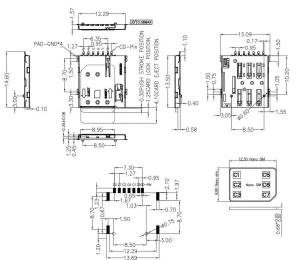
#### Plating Contact

Shell

## Electrical

Current Rating
Voltage Rating
Ambient Temperature Range
Contact Resistance
Insulation Resistance
Mating Cycles
Contact Resistance

## Diagram





CRICUIT DIAGRAM FOR CARD DETECT SWITCH

Sim Pin Assignment			
Pin No.	Name		
C1	VCC		
C2	RST		
C3	CLK		
C5	GND		
C6	VPP		
C7	I/O		

# Part Number Table

	Description	Part Number	
mensions : Millimetres	Nano Sim Card Connector, Push-Push	MP013698	

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